

# HZL6.2Z4

## Silicon Planar Zener Diode for Surge Absorb

REJ03G0409-0100

Rev.1.00

Oct 01, 2004

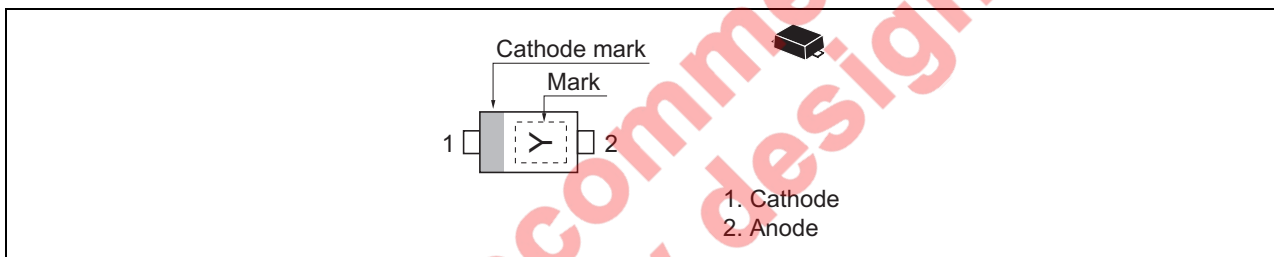
### Features

- Low capacitance ( $C = 4.0 \text{ pF max}$ ) and can protect ESD of signal line.
- Extremely small Flat Package (EFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Code
HZL6.2Z4	Y	EFP

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig.2.

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	Vz	5.90	—	6.50	V	Iz = 5 mA, 40 ms pulse
Reverse current	IR	—	—	3	μA	VR = 5.5 V
Capacitance	C	—	—	4.0	pF	VR = 0 V, f = 1 MHz
Dynamic resistance	rd	—	—	60	Ω	Iz = 5 mA
ESD-Capability *1	—	8	—	—	kV	C = 150 pF, R = 330 Ω, Both Forward and reverse direction 10 pulse

Notes: 1. Failure criterion ; IR &gt; 3 μA at VR = 5.5 V.

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Not recommended for new design

Main Characteristic

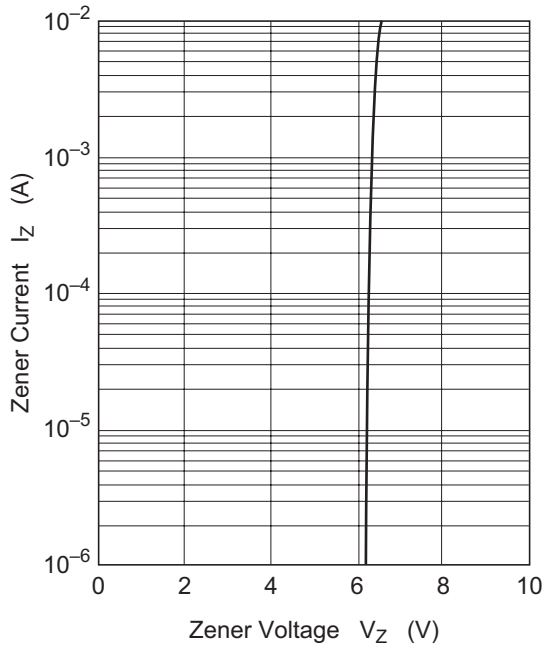


Fig.1 Zener current vs. Zener voltage

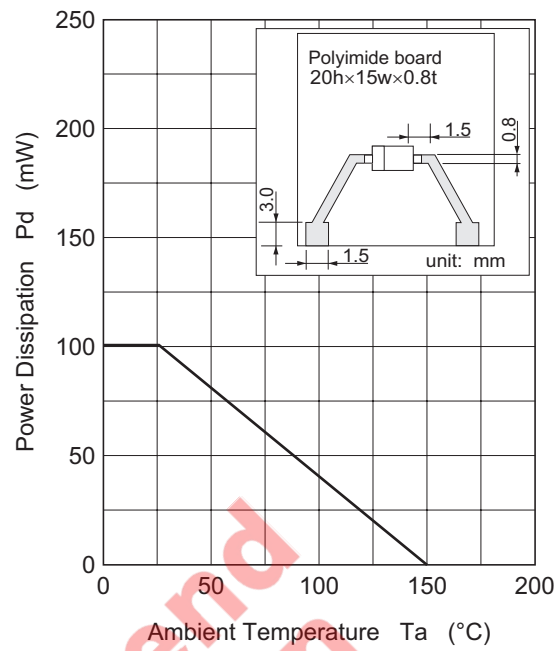


Fig.2 Power Dissipation vs. Ambient Temperature

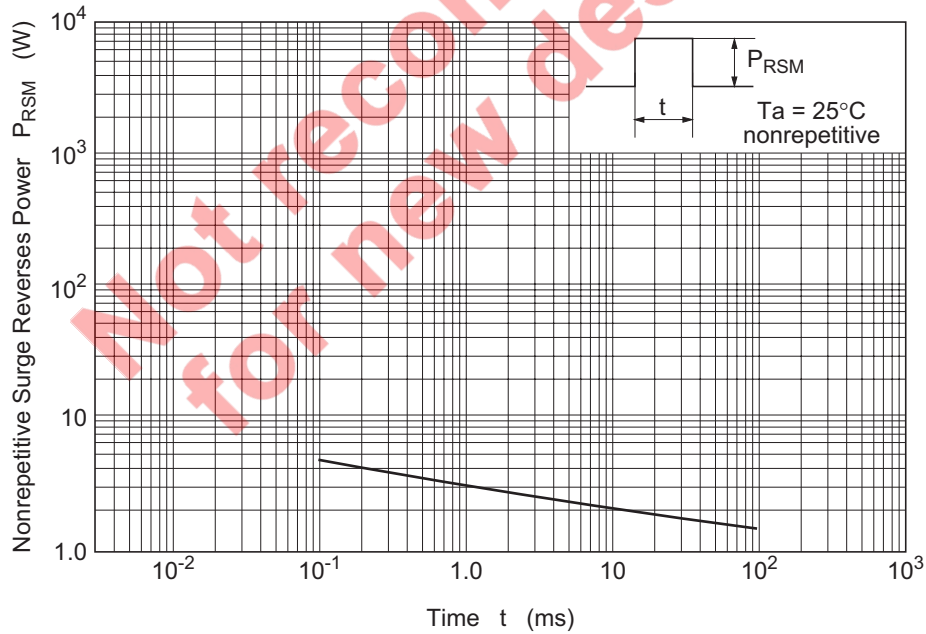
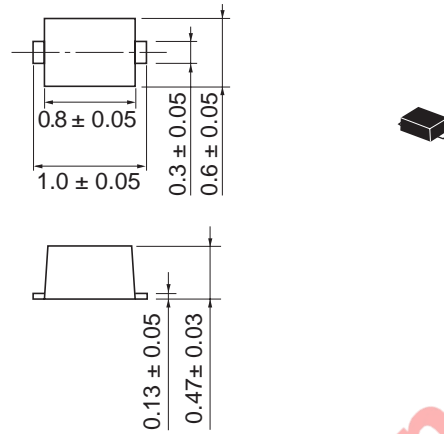


Fig.3 Surge Reverse Power Ratings

## Package Dimensions

As of January, 2003  
Unit: mm

Package Code	EFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0007 g

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